

APPROVAL SHEET

Approval Specification	Customer's Approval Certificate		
TO:	Please return this copy as a certification of your approval		
Part No.:	Checked & Approved by:		
Customer's Part No.:	Date:		

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Part No.	:	SF9152
Pages	:	6
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Revision	:	1.0



Prepared by:	
Checked by:	
Approved by:	

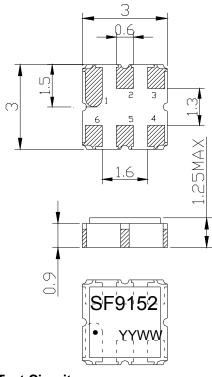
Application

- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 21 MHz

Features

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 3.00x3.00x1.25mm³
- Package Code DCC6C
- Electrostatic Sensitive Device(ESD)

Package Dimensions (Unit: mm)



Test Circuit



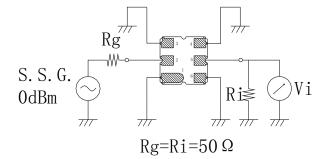
Pin Configuration

Pin No.	Description
2	Input
5	Output
1,3,4,6	Ground

Marking Description

s	Trademark			
F	SAW Filter			
9152	Part Number			
•	Pin 1			
YYWW	Year Code & Week Code			

*Fig: If the products produced in 06th week of 2012, The year code & week code is 1206.



Please read notes at the end of this document.

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2013/2/25

Performance

Maximum Rating

Item		Value	Unit
DC Voltage	V _{DC}	3	V
Operation Temperature	Т	-40 ~ +85	$^{\circ}$
Storage Temperature	T _{stg}	-55 ~ +125	${\mathbb C}$
RF Power Dissipation	Р	10	dBm

Electronic Characteristics

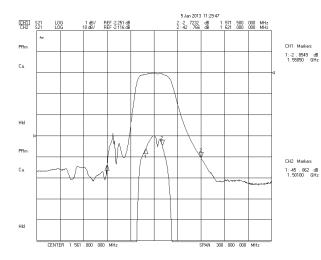
Test Temperature: $25^{\circ}C \pm 2^{\circ}C$

Terminating source impedance: 50Ω Terminating load impedance: 50Ω

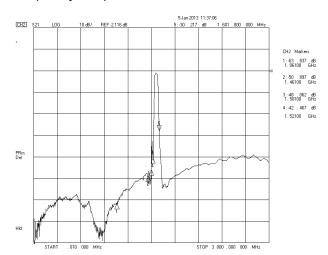
Item	Minimum	Typical	Maximum	Unit	
Center Frequency	fc		1561.00		MHz
Insertion Loss(min)	IL		2.3	2.5	dB
Insertion Loss 1550.50 - 1571.50MHz	IL		2.8	3.5	dB
Amplitude Ripple (p-p) 1550.50 - 1571.50MHz	△a		0.5	0.8	dB
Group Delay Ripple 1550.50 - 1571.50MHz	GDR		10.0	30.0	ns
Absolute Attenuation	а				
DC-1061.00 MHz		50.0	55.0		dB
1061.00-1461.00 MHz		35.0	45.0		dB
1461.00-1501.00 MHz		35.0	45.0		dB
1501.00 -1521.00 MH		20.0	30.0		dB
1601.00 -1621.00 MH		20.0	30.0		dB
1621.00 -1641.00 MH		35.0	40.0		dB
1641.00-2061.00 MHz		35.0	40.0		dB
2061.00-3000.00 MHz		30.0	35.0		dB
Input VSWR 1550.50 - 1571.50MHz			1.8:1	2.0:1	/
Output VSWR 1550.50 - 1571.50MHz			1.8:1	2.0:1	/

Frequency Characteristics

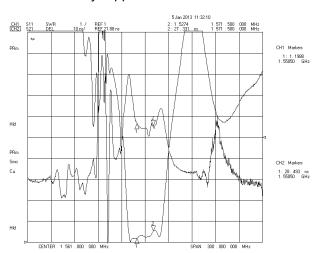
Frequency Response



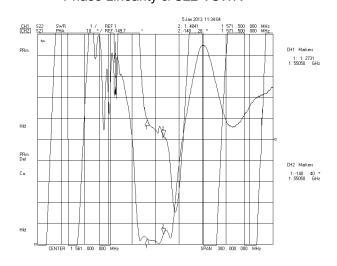
Frequency Response (wideband)



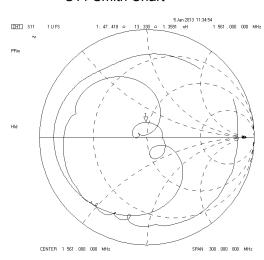
Delay Ripple & S11 VSWR



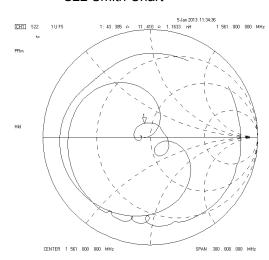
Phase Linearity & S22 VSWR



S11 Smith Chart



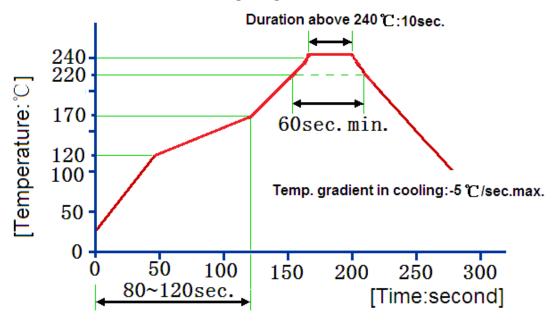
S22 Smith Chart



Reliability (The SAW components shall remain electrical performance after tests)

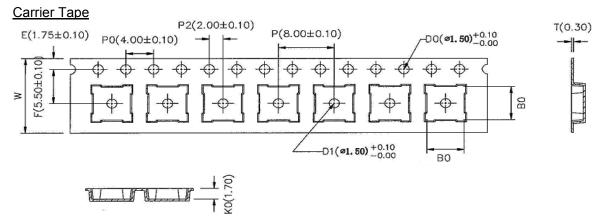
No.	Test item	Test condition		
1	Temperature	(1) Temperature: 85℃±2℃, Duration: 250h, Recovery time: 2h±0.5h		
Ī	Storage	(2) Temperature: –55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h		
2	Humidity Test	Conditions: 60℃±2℃, 90~95% RH Duration: 250h		
3	Thormal Chook	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch		
3	Thermal Shock	time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.		
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm		
_	Vibration Latigue	Directions: X,Y and Z Duration: 2h		
5	Drop Test	Cycle time: 10 times Height: 1.0m		
		Temperature: 245 ℃ ±5 ℃ Duration: 3.0s5.0s		
6 Solder Ability Test		Depth: DIP2/3 , SMD1/5		
		(1)Thickness of PCB:1mm , Solder condition: 260 ℃±5 ℃ , Duration: 10±1s		
7	Resistance to Soldering Heat	(2)Temperature of Soldering Iron: 350 ℃±10 ℃ , Duration: 3~4s ,		
		Recovery time: 2 ± 0.5h		

Recommended Reflow Soldering Diagram



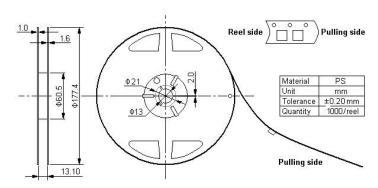
Reflow cycles:3 cycles max.

Packing Information



* B0: 5.35 for QCC8C; 4.15 for DCC6/QCC8B; 3.35 for DCC6C/QCC8D

Reel Dimensions



Outer Packing

Туре	Quantity	Dimension	Description	Weight
Internal box	1000	190×188×42	carton box 2 reel / internal box	0.18
External box	10000	235×205×210	5 boxes / external box	1.80

Unit: mm Unit: kg

Notes

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may be soldered. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.